

In the Claims

1. (Currently Amended) Dicing tape comprising a tackifiable adhesive layer which is composed mainly of a soluble polyimide and an epoxy-modified polysiloxane at 1 – 100 parts by weight with respect to 100 parts by weight of the soluble polyimide, formed on a release film and has a peel strength of 0.02 N/mm or greater as the adhesive strength at ~~near~~a room temperature of (20 - 50°C) and a cured peel strength of 0.3 N/mm or greater.

2. (Currently Amended) ~~Dieing~~The dicing tape according to claim 1, wherein the peel strength (~~adhesive strength~~) is 0.02 – 1 N/mm and the cured peel strength is 0.3 – 1.6 N/mm.

3. (Currently Amended) ~~Dieing~~The dicing tape according to claim 1, wherein the volume resistivity indicating the electrical insulating property of the cured tackifiable adhesive layer is $10^{14} \Omega \cdot \text{cm}$ or greater.

4. (Currently Amended) ~~Dieing~~The dicing tape according to claim 1, wherein the thickness of the cured tackifiable adhesive layer is 5 – 50 μm .

5. (Currently Amended) ~~Dieing~~The dicing tape according to claim 1, wherein the polyimide is a polyimidesiloxane.

6. (Currently Amended) ~~Dieing~~The dicing tape according to claim 1, which is used as a bonding sheet after dicing.

7. (Cancelled)

8. (Currently Amended) ~~A~~The dicing method according to claim ~~79~~, wherein attaching and dicing is performed at a temperature of 20 - 50°C.

9. (New) A dicing method comprising:
attaching circuit-formed silicon wafer to dicing tape comprising a tackifiable adhesive layer, which is composed of a soluble polyimide and an epoxy-modified polysiloxane at 1 – 1—parts by

weight with respect to 100 parts by weight of the soluble polyimide, formed on a release film, and dicing to form separate individual IC chips.